Docket No.: 27-013

DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I hereby declare that:

My residence, post office address, and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter claimed and for which a patent is sought on the invention entitled:

STRIP-FABRICATED FLIP CHIP IN PACKAGE AND FLIP CHIP IN SYSTEM HEAT SPREADER ASSEMBLIES AND FABRICATION METHODS THEREFOR

the specification o	f which					
is attached her	eto					
was filed on as Application Serial No and was amended on (if applicable).						
I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.						
America before the the same was not prior to this appli	is invention there in public use or or cation. I acknowle	he same was ever known or to for more than one year prior in sale in the United States of edge the duty to disclose infor accordance with title 37, Contact the contact of	r to this app America m ormation w	lication, and to ore than one y hich is known	that rear 1 to	
or Section 365(b) 365(a) of any PC the United States	of any foreign ap I international app , listed below and 's certificate have	fits under Title 35, United Sta plication(s) for patent or inve plication which designated at d have also identified below ing a filing date before that	ntor's certi least one c any foreig	ficate, or Sectountry other to n application	ion han for	
Prior Foreign Ap	plication(s):					
Number	Country	Day/Month/Yest filed	Priority <u>Yes</u>	Claimed <u>No</u>		
I hereby claim the application(s) lists		USC 119(e) of any United Sta	tes provisio	onal		
Prior Provisional	Application(s):					
Application Nun	iber <u>Filin</u>	g Date				
States application	(s), or Section 36	Citle 35, United States Code, 5(c) of any PCT international sofar as the subject matter of	application	n designating	the	

I hereby claim the benefit under Title 35, United States Code, Section 120 of any United States application(s), or Section 365(c) of any PCT international application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT international application in the manner provided by the first paragraph of Title 35, United States Code, Section 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal

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Regulations, Section 1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

Prior U.S. Application(s):

Serial No.

Filing Date

Status: Patented, Pending, Abandoned

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I hereby revoke any previous Powers of Attorney and appoint the following attorney(s) and/or agent(s), each said individual being a member or associate of The Law Offices of Mikio Ishimaru or being employed by ST Assembly Test Services Ltd.:

Mikio Ishimaru

Reg. No. 27,449

William D. Zahrt, II

Reg. No. 26,070

Date: Tan. 19, 2004

for so long as they remain with such law offices or company with full power of substitution and revocation, to prosecute this application and to transact in connection therewith all business in the Patent and Trademark Office and before competent International Authorities; said appointment to be to the exclusion of myself and my other attorney(s); and all future correspondence should be addressed to:

> Mikio Ishimaru The Law Offices of Mikio Ishimaru 1110 Sunnyvale - Saratoga Rd., Suite Al Sunnyväle, California 94087

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Tie Wang

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4		
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